

General information

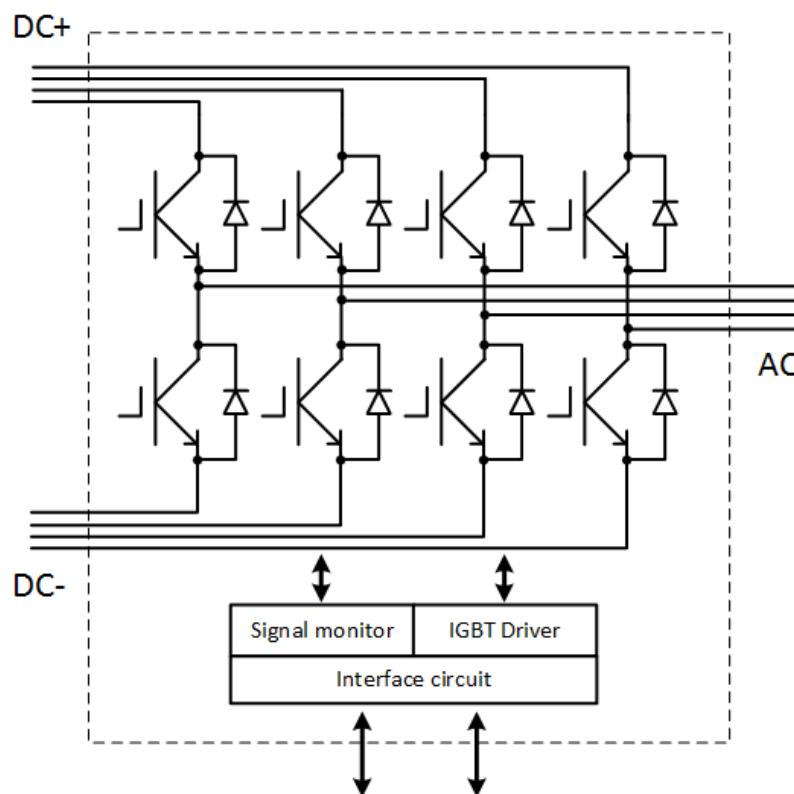
IPM for typical voltages up to 690 V_{RMS}
Rated output current 1550 A_{RMS}

Features

- Integrated current, voltage and temperature measurement
- Tvjop max=150°C
- Real time Tvj simulation
- IGBT4 technology
- Smart protection
- TIM and pressfit technology
- Modbus interface
- 100% tested IPM
- ROHS compliant
- Integrated chip current : 2400A
- Integrated chip voltage: 1700V



Topology	half bridge
Application	Energy Storage, Smart Grid, Wind, Drives, Solar
Heatsink	water cooled
Implemented sensors	voltage, current, temperature
Driver signals IGBT	+15V
Approvals	UL61800-5-1
Sales - name	IFF2400P17LE440988



prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

Preliminary data

Characteristic values

IGBT characteristic value

			min.	typ.	max.	
Collector-emitter voltage	$I_C = 2400\text{ A}$, $T_{vj} = 25^\circ\text{C}$	$V_{ce\text{ sat}}$		1.95	2.30	V
	$I_C = 2400\text{ A}$, $T_{vj} = 150^\circ\text{C}$			2.45		V
Turn on energy loss	$I_C = 2400\text{ A}$, $V_{DC} = 900\text{ V}$, $L_S = 17\text{ nH}$, $T_{vj} = 25^\circ\text{C}$	E_{on}		730		mJ
	$I_C = 2400\text{ A}$, $V_{DC} = 900\text{ V}$, $L_S = 17\text{ nH}$, $T_{vj} = 150^\circ\text{C}$			1170		mJ
Turn off energy loss	$I_C = 2400\text{ A}$, $V_{DC} = 900\text{ V}$, $L_S = 17\text{ nH}$, $T_{vj} = 25^\circ\text{C}$	E_{off}		460		mJ
	$I_C = 2400\text{ A}$, $V_{DC} = 900\text{ V}$, $L_S = 17\text{ nH}$, $T_{vj} = 150^\circ\text{C}$			810		mJ
Thermal resistance junction to ambient for diode due diode housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ IGBT} \leftarrow \text{IGBT}}$		0.0254		K/W
Thermal resistance junction to ambient for IGBT due IGBT housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ IGBT} \leftarrow \text{diode}}$		0.0135		K/W

Notes

Cooling fluid = 48% water / 52% mono-ethylene glycol,
For further details about the thermal resistance please refer to the handbook.

Diode characteristic value

			min.	typ.	max.	
Forward voltage	$I_C = 2400\text{ A}$, $T_{vj} = 25^\circ\text{C}$	V_F		1.80	2.20	V
	$I_C = 2400\text{ A}$, $T_{vj} = 150^\circ\text{C}$			1.95		V
Reverse recovery energy	$I_C = 2400\text{ A}$, $V_{DC} = 900\text{ V}$, $L_S = 17\text{ nH}$, $T_{vj} = 25^\circ\text{C}$	E_{rec}		250		mJ
	$I_C = 2400\text{ A}$, $V_{DC} = 900\text{ V}$, $L_S = 17\text{ nH}$, $T_{vj} = 150^\circ\text{C}$			530		mJ
Thermal resistance junction to ambient for diode due diode housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ diode} \leftarrow \text{diode}}$		0.0358		K/W
Thermal resistance junction to ambient for IGBT due IGBT housing	per IPM switch, flow rate: 15l/min	$R_{thja\text{ diode} \leftarrow \text{IGBT}}$		0.0134		K/W

Notes

Cooling fluid = 48% water / 52% mono-ethylene glycol,
For further details about the thermal resistance please refer to the handbook.

Absolute maximum rated values

Collector-emitter voltage	IGBT; $T_{vj} = 25^\circ\text{C}$	V_{CES}	1700	V
Repetitive peak reverse voltage	Diode; $T_{vj} = 25^\circ\text{C}$	V_{RRM}	1700	V
DC link voltage		V_{DC}	1450	V
Peak switching current		I_{peak}	4000	A
Insulation test voltage	$f = 50\text{ Hz}$, $t = 60\text{ s}$	V_{ISOL}	3.4	kV _{RMS}
Junction temperature	under switching conditions	T_{vjop}	150	$^\circ\text{C}$
Operational ambient temperature min.		T_{amb}	-40	$^\circ\text{C}$
Switching frequency operation values		f_{sw2}	10	kHz

Notes

prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

Preliminary data

Operation values

			min.	typ.	max.	
Rated continuous current	$V_{DC} = 1100 \text{ V}$, $V_{AC} = 690 \text{ V}_{RMS}$, $\cos(\varphi) = 0.85$, $f_{AC \text{ sine}} = 50 \text{ Hz}$, $f_{sw} = 3000 \text{ Hz}$, $T_{inlet} = 40^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$	I_{AC}		1550		A_{RMS}
Power losses	$I_{AC} = 1550 \text{ A}$, $V_{DC} = 1100 \text{ V}$, $V_{AC} = 690 \text{ V}_{RMS}$, $\cos(\varphi) = 0.85$, $f_{AC \text{ sine}} = 50 \text{ Hz}$, $f_{sw} = 3000 \text{ Hz}$, $T_{inlet} = 40^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$	P_{loss}		8900		W

Controller interface

			min.	typ.	max.	
Auxiliary voltage		V_{aux}	19.2	24	28.3	V
Auxiliary power requirement	$V_{aux} = 24 \text{ V}$	P_{aux}			48	W
Digital input level		$V_{in \text{ low}}$			2	V
		$V_{in \text{ high}}$	8.5		16	V
Digital output level	max. 1 mA	$V_{out \text{ low}}$			2	V
		$V_{out \text{ high}}$	13.5	15	16.5	V
Interlock time	default value	$t_{interlock}$		4		μs
Propagation delay for PWM	default value	t_{prop}		4		μs
Analog output for phase current	for 1550A	$V_{lac \text{ ana}}$		3.69		V
Over current shut down	default value, response time 15 μs	$I_{ac \text{ trip}}$		4200		A
Analog DC link voltage sensor output	load max 5 mA, @ 1100 V	$V_{DC \text{ ana}}$		7.86		V
Over voltage shut down	default value, response time 500 μs	$V_{dc \text{ trip}}$		1340		V
Chip over temperature shut down	default value, response time 1000 μs	$T_{vj \text{ trip}}$		150		$^\circ\text{C}$
Analog output for junction temperature	for 150 $^\circ\text{C}$	$V_{Tvj \text{ ana}}$		10		V
PCB ambient over temperature shut down	default value, response time 1 s	$T_{pcb \text{ err}}$		85		$^\circ\text{C}$
Serial BUS	Modbus, RS485			19200		Bit/s

prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

Preliminary data

System data

			min.	typ.	max.	
EMC robustness	according to IEC61800 at named interfaces	power	V_{Burst}	2		kV
		control	V_{Burst}	2		kV
Storage temperature		T_{stor}	-40		85	°C
Operational ambient temperature		$T_{op\ amb}$	-40		65	°C
Stray inductance		L_s		8.5		nH
Lead resistance		$R_{CC\ EE}$		1.2		mΩ
Impuls test voltage	Power to logic side, acc.IEC 61800-5-1			12		kV
Isolation test voltage	RMS, f = 50 Hz, t = 60 s	V_{ISOL}		3.4		kV
Creepage distance	Power side to heatsink across housing			13		mm
Clearance	Power side to heatsink			8		mm
Protection degree				IP00		
Pollution degree				2		
Dimensions	width x depth x height		215	338	115	mm
Weight				6.1		kg

Notes

Partial discharge test, power side to logic side, according to IEC 61800-5-1, $TE > 1920V$

Housing CTI > 175

For further details about the system data please refer to the handbook.

Heatsink water cooled

			min.	typ.	max.	
Water flow	according to coolant specification from Infineon	$\Delta V/\Delta t$		15		dm³/min
Water pressure				6	8	bar
Water pressure drop	at 15 dm³/min water flow	Δp		120		mbar
Coolant inlet temperature		T_{inlet}	-40		60	°C

Notes

Cooling fluid = 48% water / 52% mono-ethylene glycol (MEG)

prepared by: OW

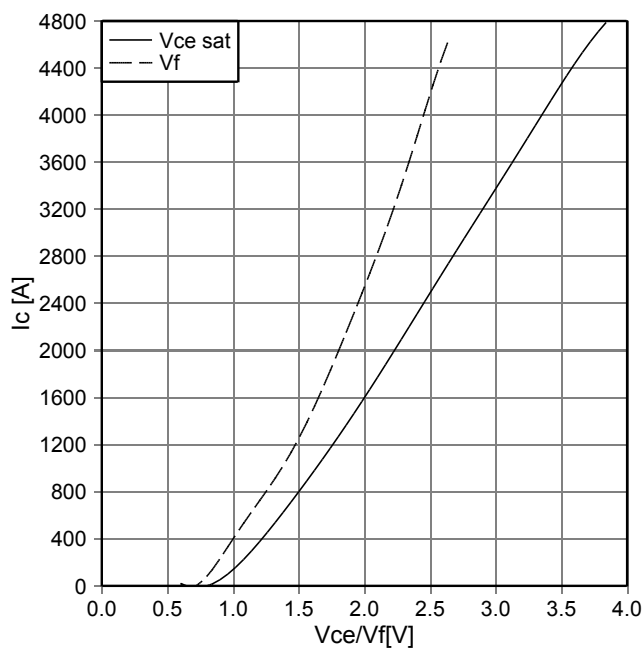
date of publication: 2018-07-25

approved by: ZF

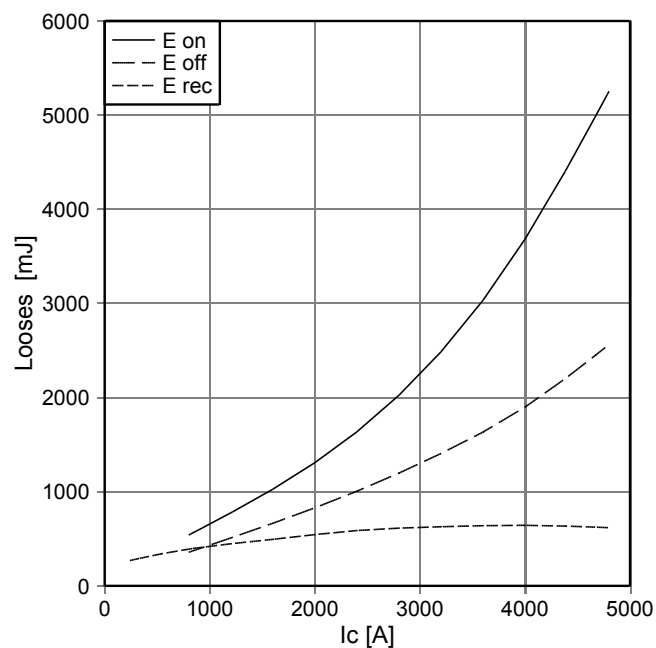
revision: 2.3

Preliminary data

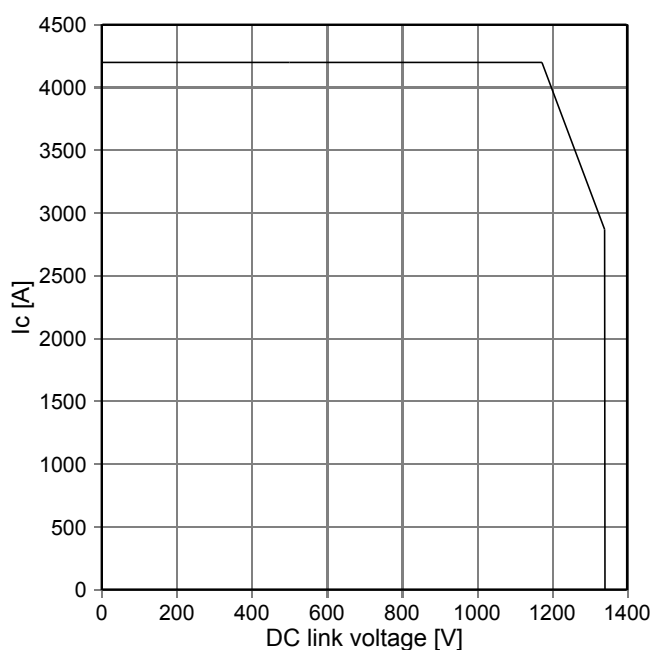
output characteristic IGBT/Diode
 $T_{vj} = 150^{\circ}\text{C}$



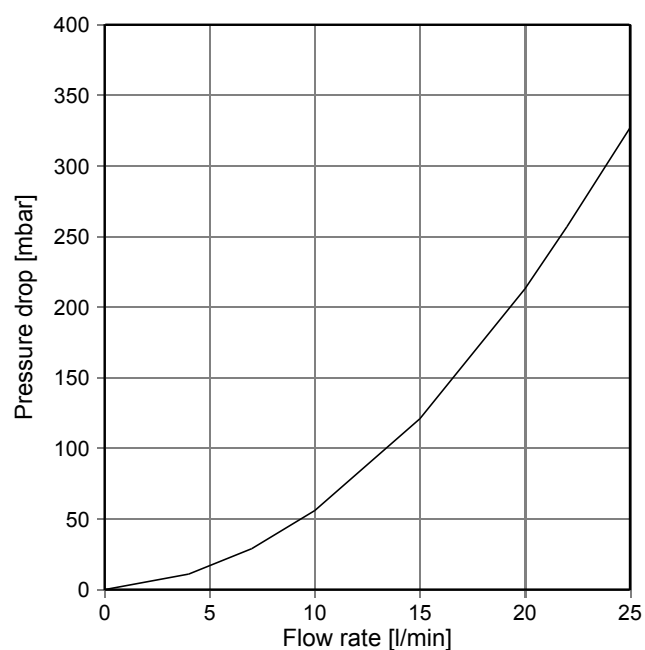
switching losses, Eon, Eoff, Erec
 $V_{dc} 1100\text{V}$, $T_{vj} = 150^{\circ}\text{C}$



safe operating area

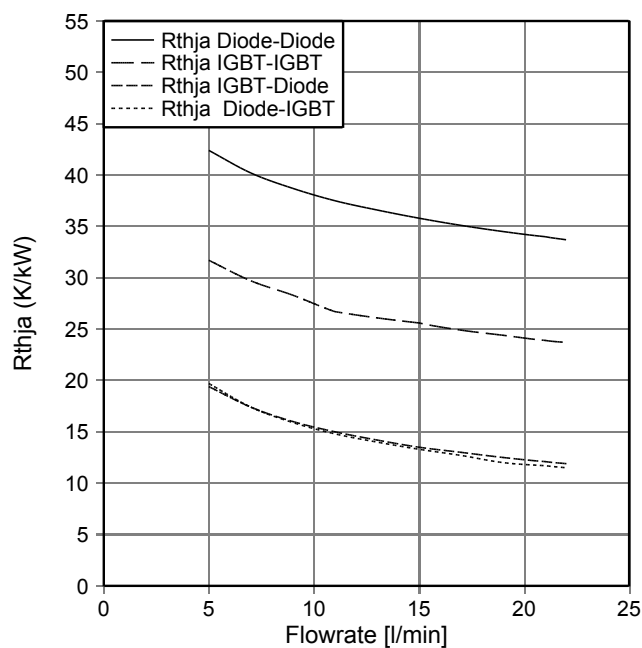


Pressure drop vs. flow rate
 $T_{inlet} = 40^{\circ}\text{C}$, 52% water / 48% MEG



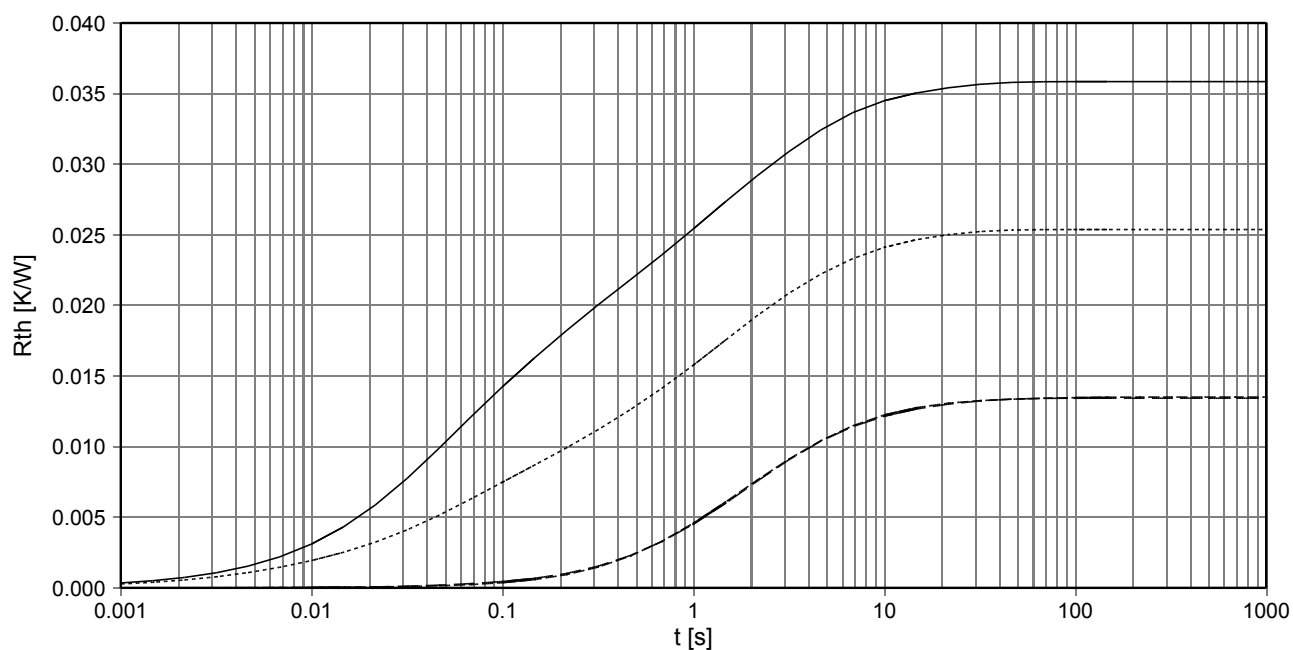
prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

Thermal resistance vs. Flow rate
T inlet=40°C, 48% water/ 52% MEG



prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

thermal impedance
 $T_{inlet} = 40^{\circ}\text{C}$, 48% water/52% MEG, 15l/min



—— Rthja Diode - Diode

i:	1	2	3	4	5	6
r_i [K/W]:	0.00115	0.00737	0.00818	0.0068	0.00975	0.0026
τ_i [s]:	0.032	0.032	0.1165	0.625	2.615	12.1

--- Rthja IGBT - IGBT

i:	1	2	3	4	5	6
r_i [K/W]:	-0.00085	0.00117	-0.00067	0.00595	0.00565	0.00218
τ_i [s]:	0.024	0.0313	0.084	1.29	3.25	13

--- Rthja IGB -Diode

i:	1	2	3	4	5	6
r_i [K/W]:	-0.001	0.00035	0.00491	0.00605	0.00275	0.00045
τ_i [s]:	0.166	0.26	1.025	2.765	7.695	40.84

..... Rthja Diode-IGBT

i:	1	2	3	4	5	6
r_i [K/W]:	0.0008	0.0046	0.003565	0.006735	0.007075	0.0026
τ_i [s]:	0.0053	0.043	0.173	0.897	2.89	10.9

prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

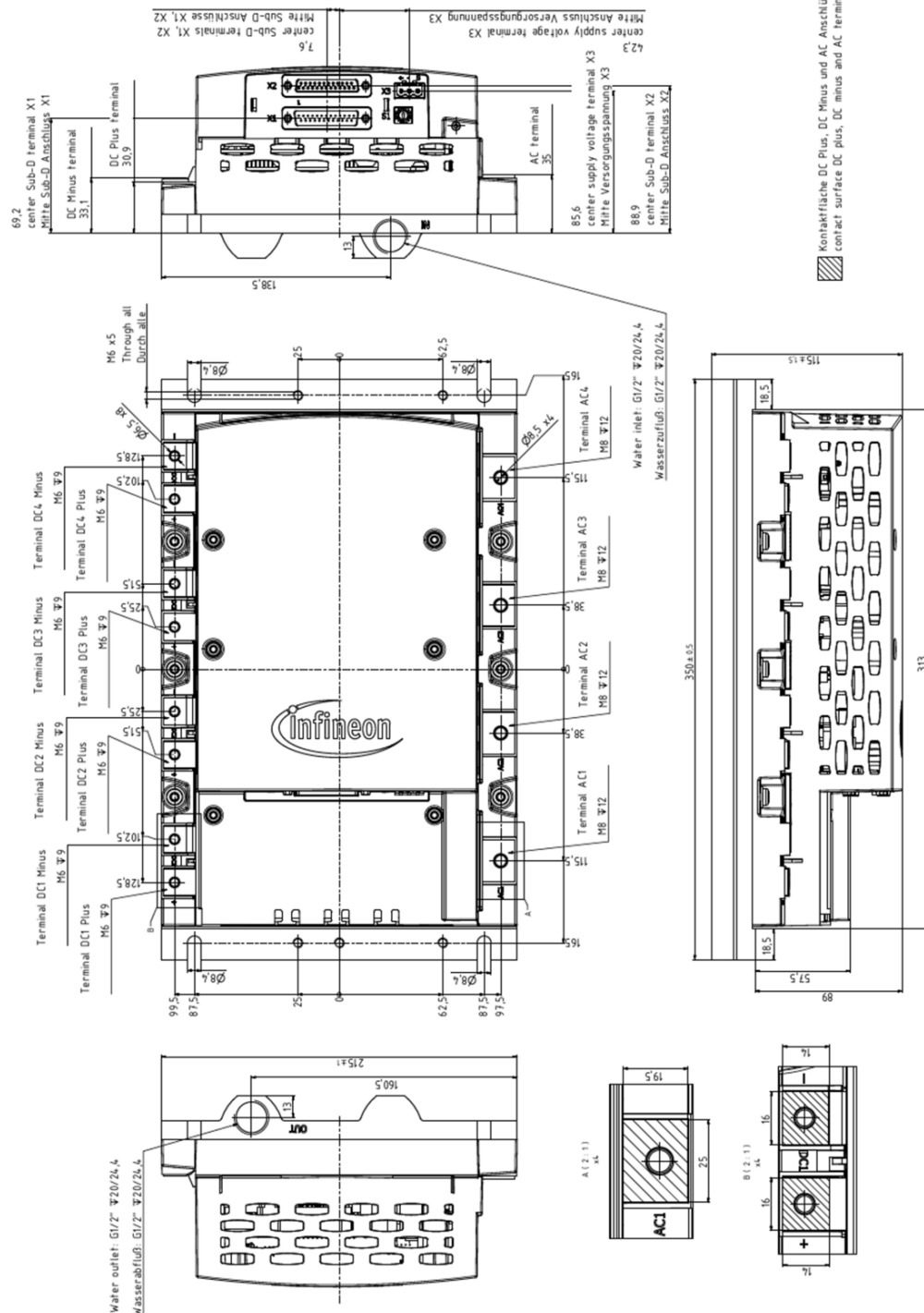
Technical Information

IFF2400P17LE440988



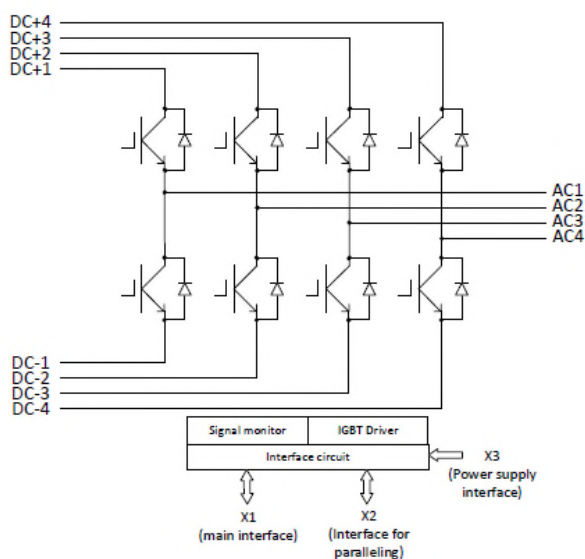
Preliminary data

Mechanical drawing



prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3

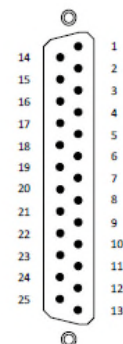
Circuit diagram



Pin configuration for X1 (main control interface)

Pin	Signal	I/O	Pin	Signal	I/O
1	24V_supply	PWR	14	GND_supply	PWR
2	24V_supply	PWR	15	GND_supply	PWR
3	+15_DC	PWR	16	GND_DC	PWR
4	Alert	OUT	17	Enable	IN
5	Fault	IN/OUT	18	Warn_OV	IN/OUT
6	ANA_Tj	ANA OUT	19	ID_det	IN/OUT
7	ANA_Vdc	ANA OUT	20	GND_ana	PWR
8	PWM_top	IN	21	PWM_bot	IN
9	Warn_OC	IN/OUT	22	GND_dig	PWR
10	ANA_Ic	ANA OUT	23	Warn_OT	IN/OUT
11	TX/RX_IN+	IN/OUT	24	TX/RX_IN-	IN/OUT
12	TX/RX_Out+	IN/OUT	25	TX/RX_Out-	IN/OUT
13	Shield			Housing is shield	

Detail information for X1, X2 and X3 refer to handbook



Sub-D 25, male
with UNC thread

Preliminary data**Terms & Conditions of usage**

The data contained in this product data sheet is exclusively intended for technically trained staff. You and your technical departments will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to such application.

This product data sheet is describing the characteristics of this product for which a warranty is granted. Any such warranty is granted exclusively pursuant to the terms and conditions of the supply agreement. There will be no guarantee of any kind for the product and its characteristics.

Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you (see www.infineon.com, sales&contact). For those that are specifically interested we may provide application notes.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the Product in aviation applications, in health or life endangering or life support applications, please notify. Please note, that for any such applications we urgently recommend

- to perform joint Risk and Quality Assessments;
- the conclusion of Quality Agreements;
- to establish joint measures of an ongoing product survey, and that we may make delivery depended on the realization of any such measures.

If and to the extent necessary, please forward equivalent notices to your customers.

Changes of this product data sheet are reserved.

Safety Instructions

Prior to installation and operation, all safety notices and warnings and all warning signs attached to the equipment have to be carefully read. Make sure that all warning signs remain in a legible condition and that missing or damaged signs are replaced. To installation and operation, all safety notices and warnings and all warning signs attached to the equipment have to be carefully read. Make sure that all warning signs remain in a legible condition and that missing or damaged signs are replaced.

prepared by: OW	date of publication: 2018-07-25
approved by: ZF	revision: 2.3